



flowPIM 0

600 V / 20 A

Topology features

- Open Emitter configuration
- Temperature sensor
- Converter+Brake+Inverter

Component features

- Easy paralleling
- Low turn-off losses
- Low collector emitter saturation voltage
- Positive temperature coefficient
- Short tail current

Housing features

- Base isolation: Al₂O₃
- Clip-in, reliable mechanical connection, qualified for wave soldering
- Convex shaped substrate for superior thermal contact
- Thermo-mechanical push-and-pull force relief
- Solder pin

Extra features

- with three-phase standard rectifier

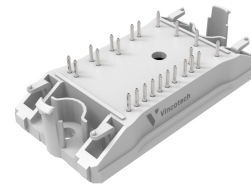
Target applications

- Industrial drives
- Embedded drives

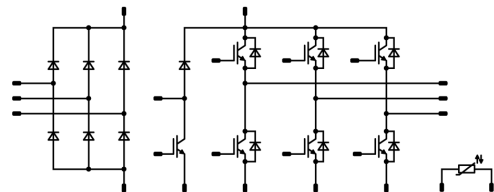
Types

- V23990-P545-A28-PM

flow 0 12 mm housing



Schematic





Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		600	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	26	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	60	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	56	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	t_{SC}	$V_{GE} = 15\text{ V}$, $V_{CC} = 360\text{ V}$ $T_j = 150\text{ °C}$	6	μs
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$

Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	21	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	40	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	37	W
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$

Brake Switch				
Collector-emitter voltage	V_{CES}		600	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	45	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	52	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	t_{SC}	$V_{GE} = 15\text{ V}$, $V_{CC} = 360\text{ V}$ $T_j = 150\text{ °C}$	6	μs
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$



Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Brake Diode				
Peak repetitive reverse voltage	V_{RRM}		600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	18	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	35	W
Maximum junction temperature	T_{jmax}		175	°C

Rectifier Diode

Peak repetitive reverse voltage	V_{RRM}		1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	34	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	200	A
Surge current capability	I^2t		200	A ² s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	44	W
Maximum junction temperature	T_{jmax}		150	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Isolation voltage	V_{isol}	AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min 12,7	mm
Clearance			9,29	mm
Comparative Tracking Index	CTI		≥ 200	

*100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	

Inverter Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00029	25	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		20	25 125	1,1	1,55 1,75	1,9 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	600		25			1,1	μA
Gate-emitter leakage current	I_{GES}		20	0		25			300	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}							1100		pF
Output capacitance	C_{oes}	$f = 1$ Mhz	0	25		25		71		pF
Reverse transfer capacitance	C_{res}							32		pF
Gate charge	Q_g	$V_{CC} = 480$ V	0/15		20	25		120		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,7		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 16$ Ω $R_{goff} = 8$ Ω	0/15	300	20	25		15		ns
						125		14		
Rise time	t_r					25		12,2		
						125		15,5		
Turn-off delay time	$t_{d(off)}$					25		198		
						125		212		
Fall time	t_f					25		100		
		125		104						
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD} = 0,454$ μC $Q_{tFWD} = 1,35$ μC				25		0,314		mWs
						125		0,427		
Turn-off energy (per pulse)	E_{off}					25		0,548		mWs
						125		0,649		



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Inverter Diode

Static

Forward voltage	V_F				20	25 125	1,25	1,81 1,76	1,95 ⁽¹⁾	V
Reverse leakage current	I_R	$V_i = 600$ V				25			27	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						2,6		K/W
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Dynamic

Peak recovery current	I_{RM}	$di/dt=2170$ A/μs $di/dt=1490$ A/μs	0/15	300	20	25		19		A
						125		21,1		
Reverse recovery time	t_{rr}					25		33		
						125		192		
Recovered charge	Q_r					25		0,454		
						125		1,35		
Reverse recovered energy	E_{rec}	25		0,06						
		125		0,271						
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$	25		1450						
		125		1050						



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Brake Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00021	25	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		15	25 125	1,1	1,64 1,87	1,9 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	600		25			0,85	μA
Gate-emitter leakage current	I_{GES}		20	0		25			300	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}							800		pF
Output capacitance	C_{oes}	$f = 1$ Mhz	0	25		25		55		pF
Reverse transfer capacitance	C_{res}							24		pF
Gate charge	Q_g		0/15		0	25		87		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,83		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 16$ Ω $R_{goff} = 8$ Ω	0/15	300	15	25		14,5		ns
						125		13,5		
Rise time	t_r					25		10,8		
						125		13,8		
Turn-off delay time	$t_{d(off)}$					25		128		
						125		145		
Fall time	t_f					25		91		
		125		94,4						
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD} = 0,518$ μC $Q_{tFWD} = 1,02$ μC				25		0,201		mWs
						125		0,282		
Turn-off energy (per pulse)	E_{off}					25		0,317		mWs
						125		0,4		



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Brake Diode

Static

Forward voltage	V_F				15	25 125	1,25	1,86 1,76	1,95 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 600$ V				25			27	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						2,75		K/W
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Dynamic

Peak recovery current	I_{RM}	$di/dt=1300$ A/μs $di/dt=1220$ A/μs	0/15	300	15	25 125		13,7 15,1		A
Reverse recovery time	t_{rr}					25 125		128 201		ns
Recovered charge	Q_r					25 125		0,518 1,02		μC
Reverse recovered energy	E_{rec}					25 125		0,103 0,215		mWs
Peak rate of fall of recovery current	$(di_r/dt)_{max}$					25 125		1310 657		A/μs

Rectifier Diode

Static

Forward voltage	V_F				8	25 125		0,983 0,889	1,21 ⁽¹⁾ 1,1 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1600$ V				25			50	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,59		K/W
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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	V_{CE} [V]	T_j [°C]	Min	Typ	Max	

Thermistor

Static

Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$A_{R/R}$	$R_{100} = 1484 \Omega$				100	-5		5	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 1 \%$						3962		K
B-value	$B_{(25/100)}$	Tol. $\pm 1 \%$						4000		K
Vincotech Thermistor Reference									I	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

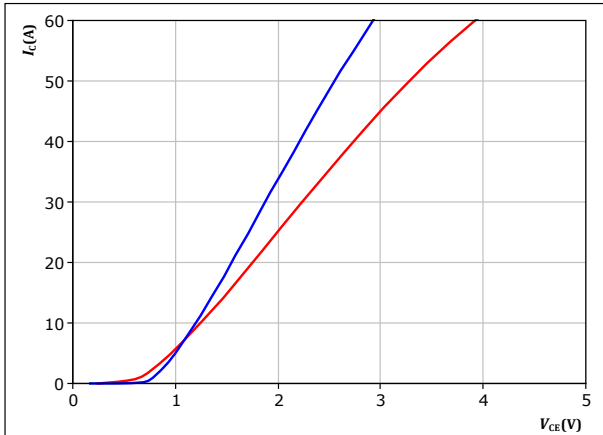


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

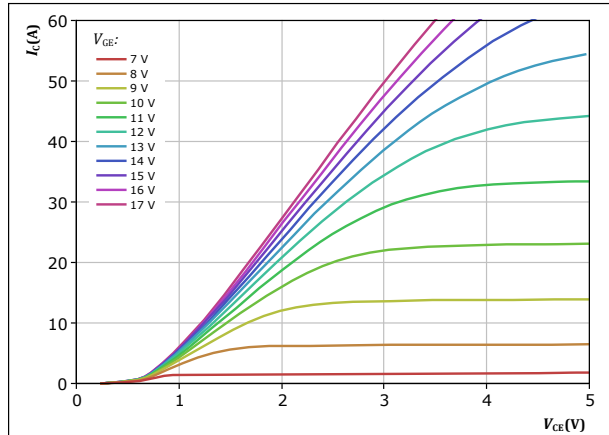


$t_p = 250 \mu\text{s}$
 $V_{GE} = 15 \text{ V}$
 $T_j: \text{— } 25^\circ\text{C}$
 $\text{— } 125^\circ\text{C}$

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

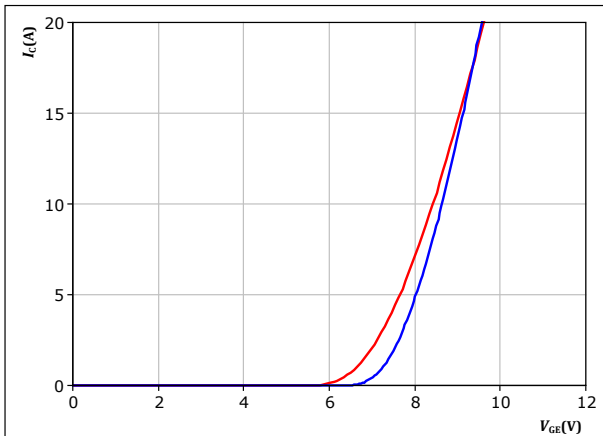


$t_p = 250 \mu\text{s}$
 $T_j = 125^\circ\text{C}$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

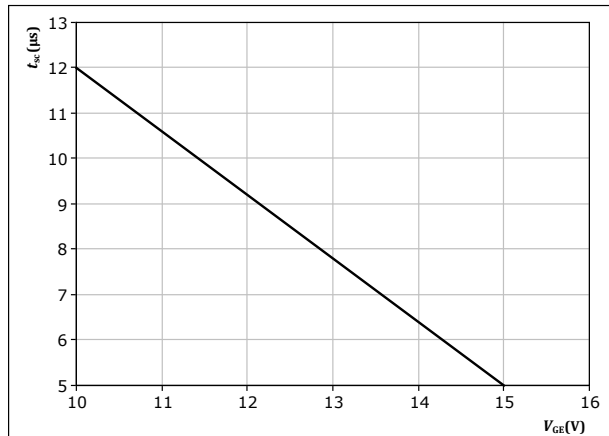


$t_p = 250 \mu\text{s}$
 $V_{CE} = 10 \text{ V}$
 $T_j: \text{— } 25^\circ\text{C}$
 $\text{— } 125^\circ\text{C}$

figure 4. IGBT

Short circuit withstand time as a function of V_{GE}

$$t_{sc} = f(V_{GE})$$



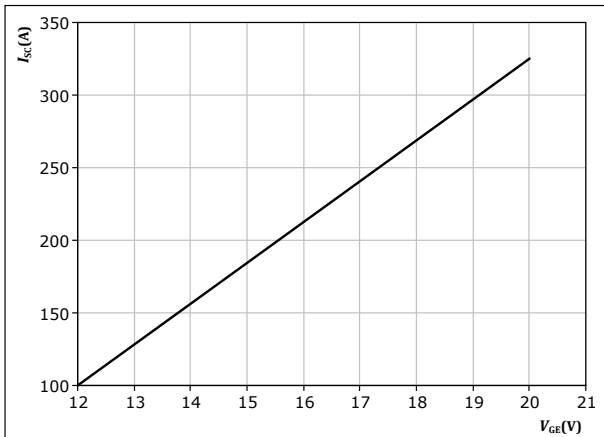
At $V_{CE} = 333 \text{ V}$
 $T_j \leq 333^\circ\text{C}$



Inverter Switch Characteristics

figure 5. IGBT

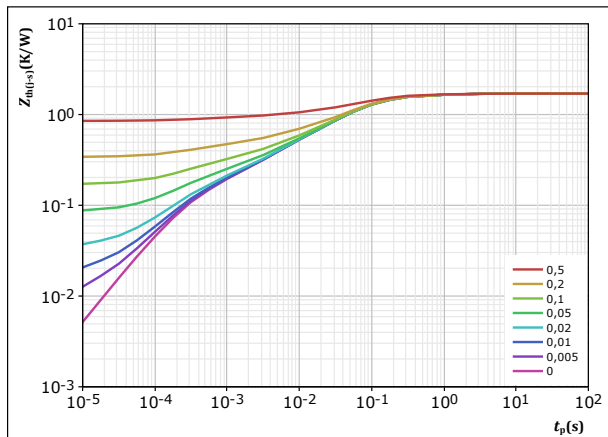
Typical short circuit current as a function of V_{GE}
 $I_{SC} = f(V_{GE})$



At $V_{CE} = 333$ V
 $T_j \leq 333$ °C

figure 6. IGBT

Transient thermal impedance as a function of pulse width
 $Z_{th(j-s)} = f(t_p)$

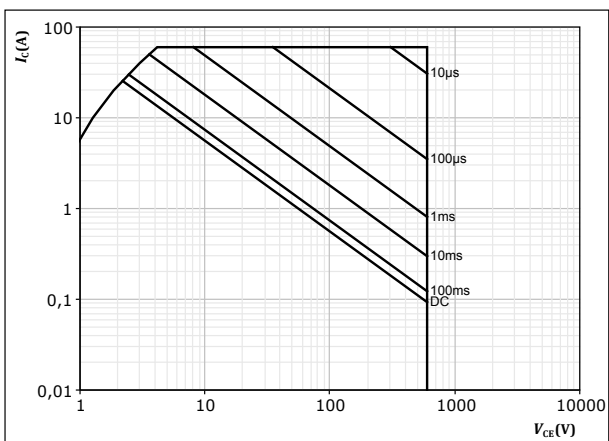


$D = t_p / T$
 $R_{th(j-s)} = 1,701$ K/W
 IGBT thermal model values

R (K/W)	τ (s)
9,97E-02	1,34E+00
3,46E-01	1,70E-01
8,15E-01	5,34E-02
2,54E-01	7,74E-03
7,70E-02	1,33E-03
1,09E-01	2,63E-04

figure 7. IGBT

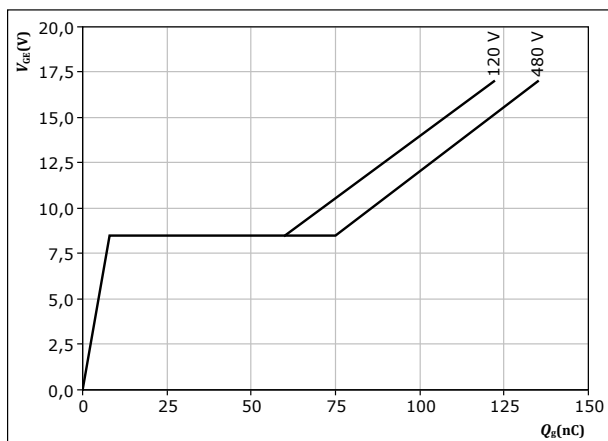
Safe operating area
 $I_C = f(V_{CE})$



$D =$ single pulse
 $T_j = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 8. IGBT

Gate voltage vs gate charge
 $V_{GE} = f(Q_g)$



$I_C = 33$ A
 $T_j = 25$ °C



Inverter Diode Characteristics

figure 9. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

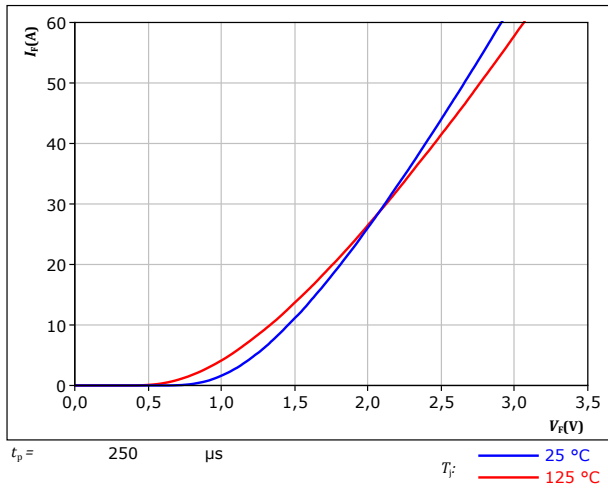
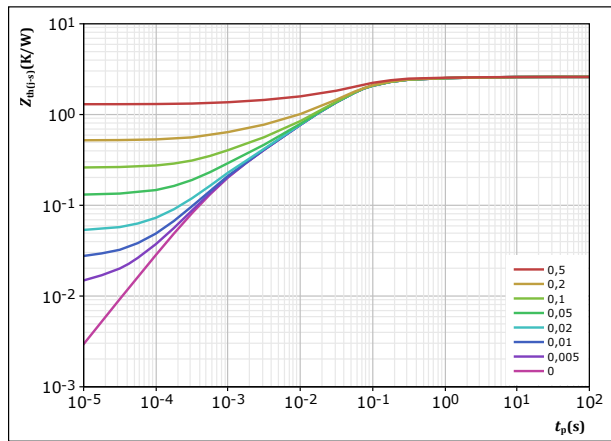


figure 10. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D =$ t_p / T
 $R_{th(j-s)} =$ 2,598 K/W
 FWD thermal model values

R (K/W)	τ (s)
6,56E-02	4,59E+00
1,58E-01	5,68E-01
8,97E-01	8,41E-02
1,05E+00	3,28E-02
2,75E-01	4,96E-03
1,51E-01	7,65E-04

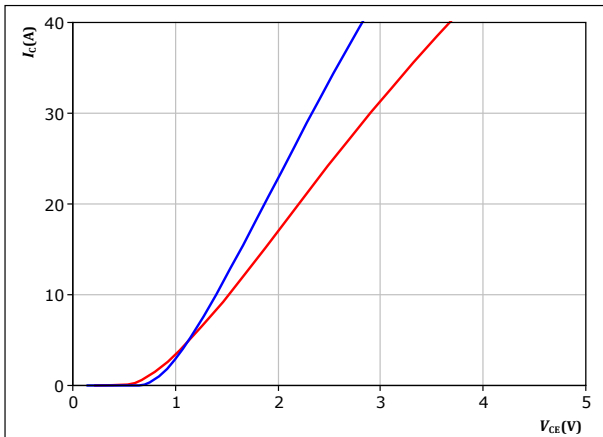


Brake Switch Characteristics

figure 11. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

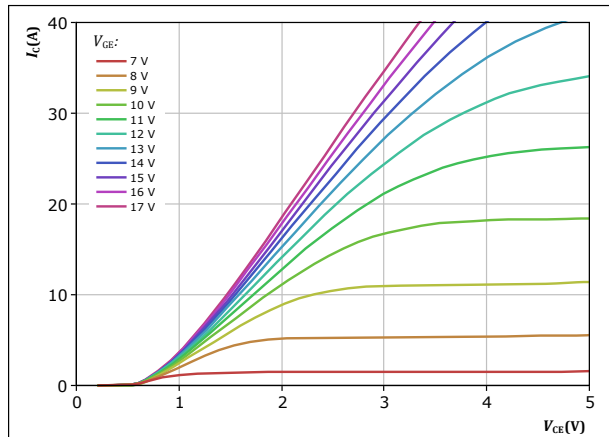


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j: 25^\circ C$ (blue), $125^\circ C$ (red)

figure 12. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

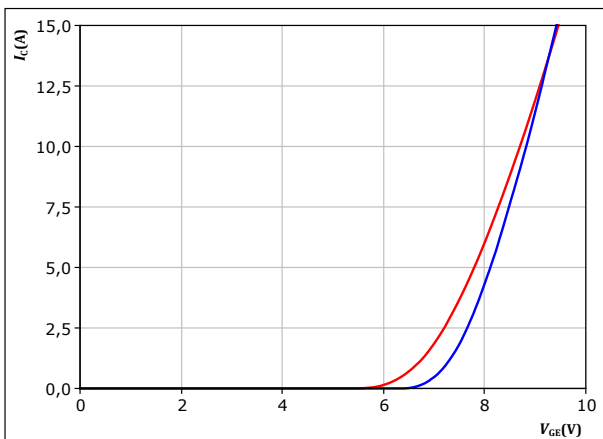


$t_p = 250 \mu s$
 $T_j = 125^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 13. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

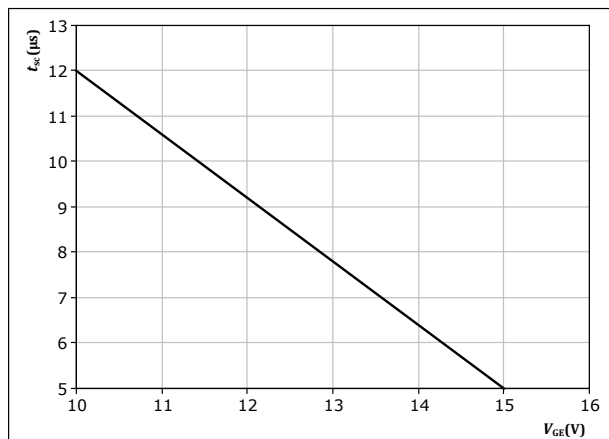


$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_j: 25^\circ C$ (blue), $125^\circ C$ (red)

figure 14. IGBT

Short circuit withstand time as a function of V_{GE}

$$t_{sc} = f(V_{GE})$$



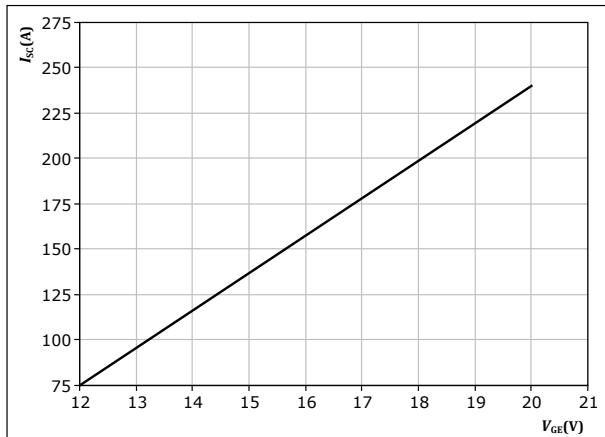
At $V_{CE} = 600 V$
 $T_j \leq 25^\circ C$



Brake Switch Characteristics

figure 15. IGBT

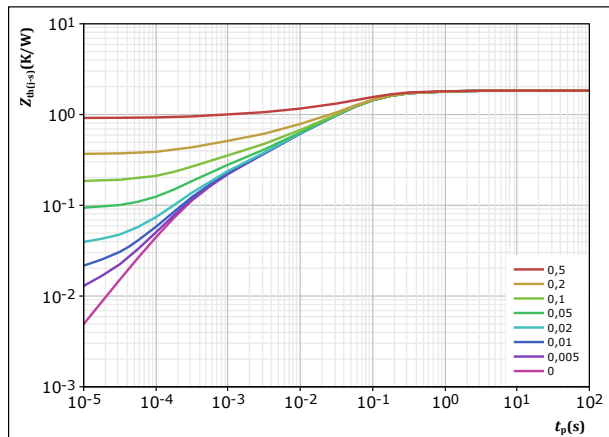
Typical short circuit current as a function of V_{GE}
 $I_{SC} = f(V_{GE})$



At $V_{CE} = 400$ V
 $T_j \leq 150$ °C

figure 16. IGBT

Transient thermal impedance as a function of pulse width
 $Z_{th(j-s)} = f(t_p)$

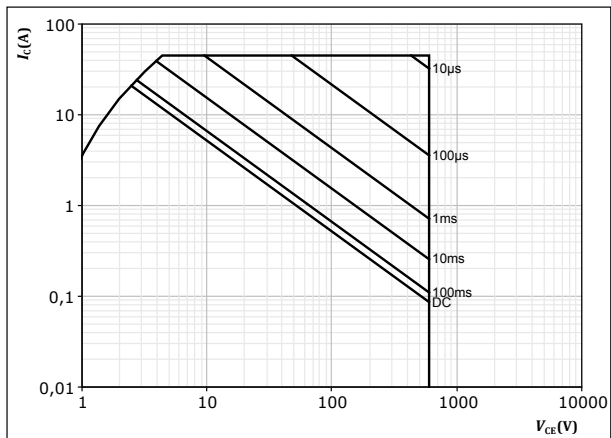


$D = t_p / T$
 $R_{th(j-s)} = 1,834$ K/W
IGBT thermal model values

R (K/W)	τ (s)
8,30E-02	1,29E+00
3,76E-01	1,56E-01
8,46E-01	5,15E-02
2,81E-01	8,16E-03
1,16E-01	2,04E-03
1,32E-01	3,43E-04

figure 17. IGBT

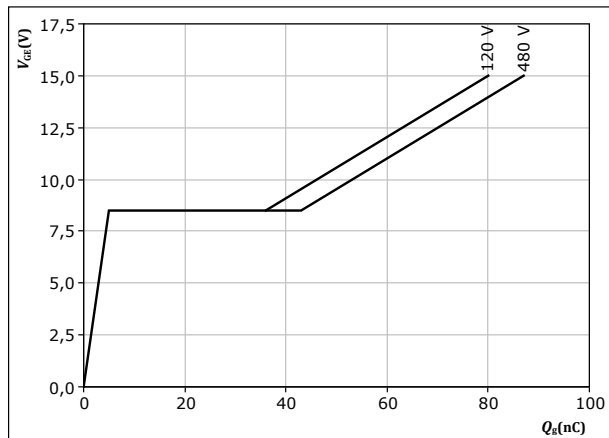
Safe operating area
 $I_C = f(V_{CE})$



$D = \text{single pulse}$
 $T_j = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 18. IGBT

Gate voltage vs gate charge
 $V_{GE} = f(Q_g)$



$I_C = 15$ A
 $T_j = 25$ °C



Brake Diode Characteristics

figure 19. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

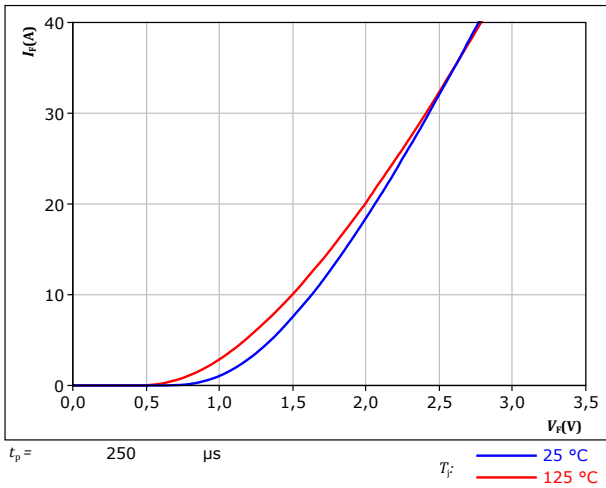
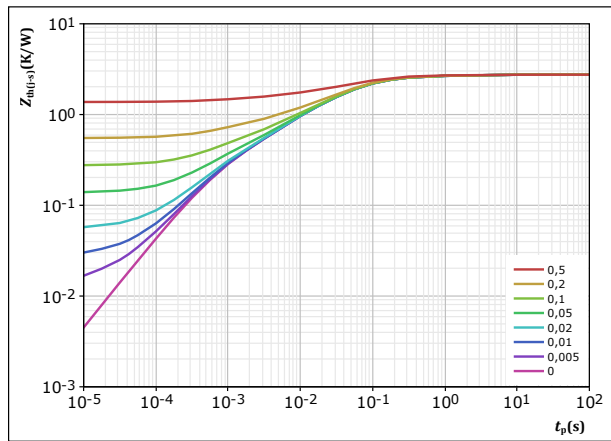


figure 20. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 2,75\text{ K/W}$
 FWD thermal model values

R (K/W)	τ (s)
1,03E-01	3,14E+00
3,03E-01	2,74E-01
1,23E+00	6,07E-02
5,94E-01	1,63E-02
3,18E-01	4,11E-03
2,02E-01	6,37E-04



Rectifier Diode Characteristics

figure 21. Rectifier

Typical forward characteristics

$$I_F = f(V_F)$$

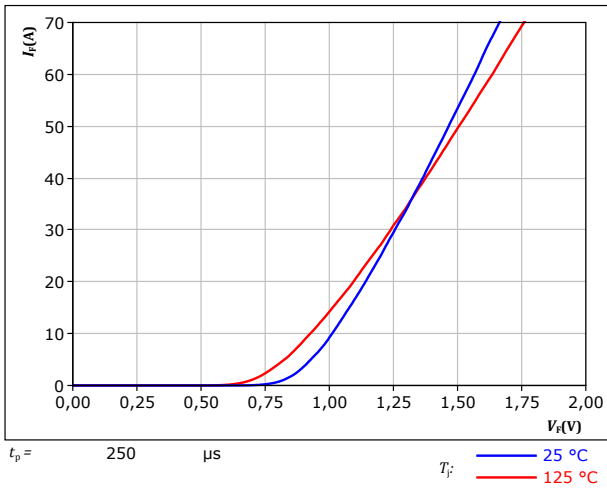
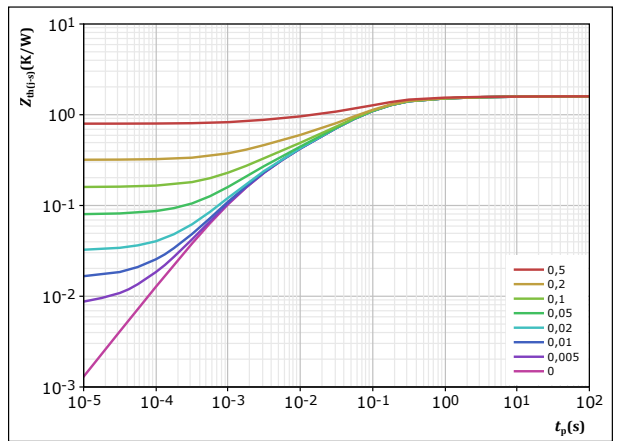


figure 22. Rectifier

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$$D = \frac{t_p}{T}$$

$$R_{th(j-s)} = 1,594 \text{ K/W}$$

Rectifier thermal model values

R (K/W)	τ (s)
3,44E-02	9,66E+00
1,12E-01	1,22E+00
5,81E-01	1,45E-01
4,89E-01	5,05E-02
2,38E-01	9,26E-03
1,22E-01	1,79E-03
1,81E-02	7,88E-04

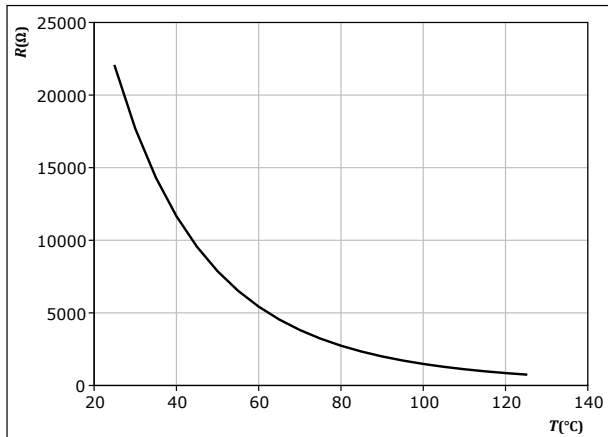


Thermistor Characteristics

figure 23. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

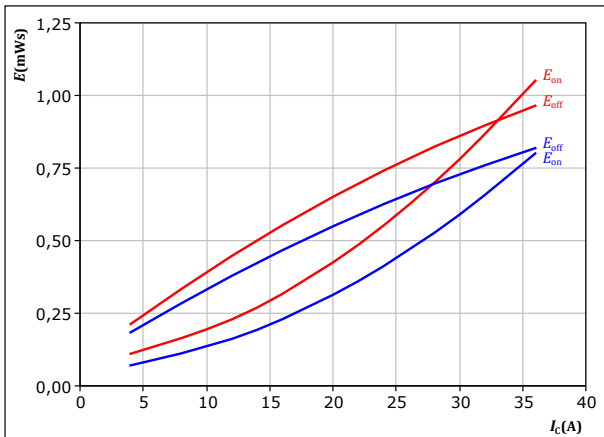




Inverter Switching Characteristics

figure 24. IGBT

Typical switching energy losses as a function of collector current
 $E = f(I_c)$

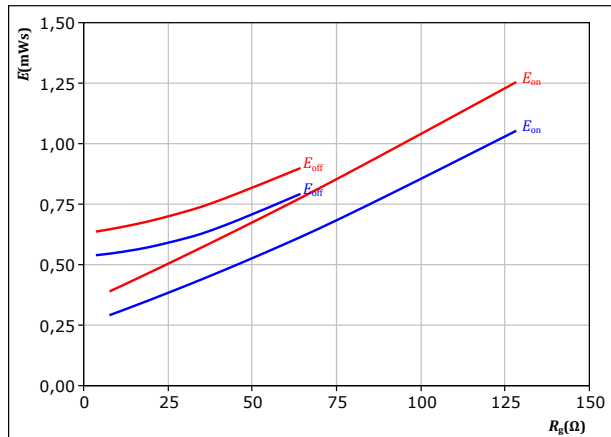


With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 16 \ \Omega$
 $R_{goff} = 8 \ \Omega$

T_j : — 25 °C
— 125 °C

figure 25. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$

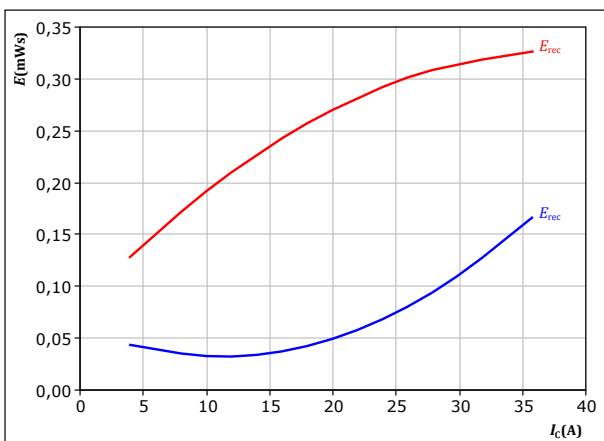


With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 20 \text{ A}$

T_j : — 25 °C
— 125 °C

figure 26. FWD

Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$

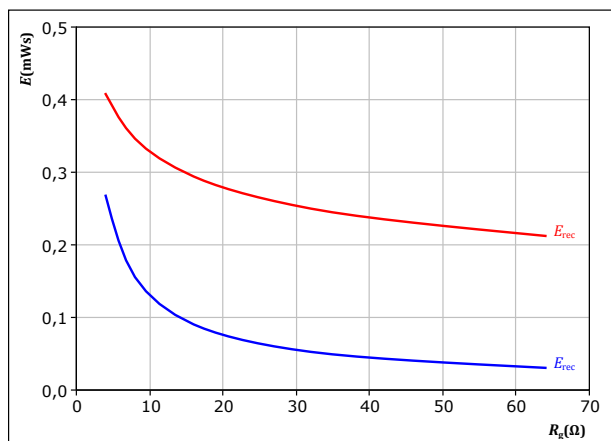


With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 16 \ \Omega$

T_j : — 25 °C
— 125 °C

figure 27. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 20 \text{ A}$

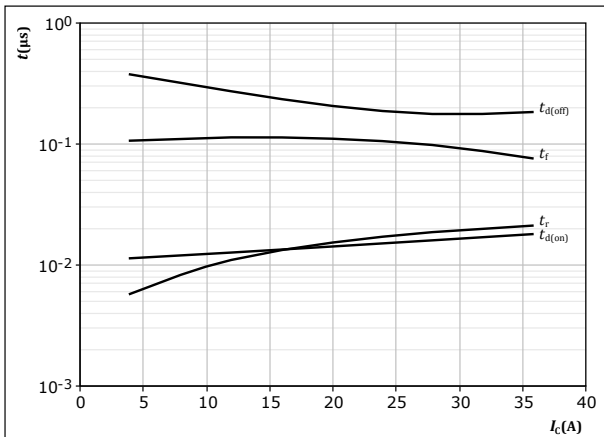
T_j : — 25 °C
— 125 °C



Inverter Switching Characteristics

figure 28. IGBT

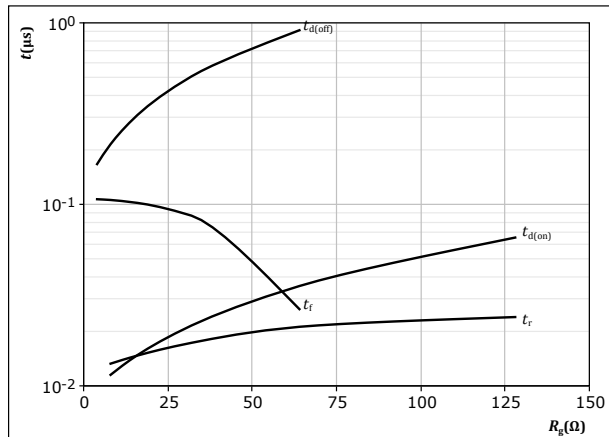
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 125 \text{ }^\circ\text{C}$
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$

figure 29. IGBT

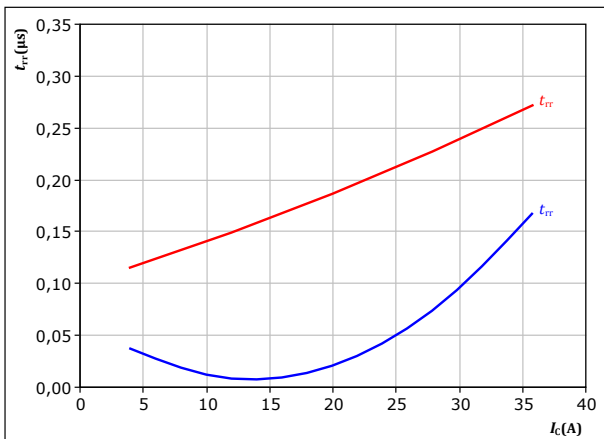
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 125 \text{ }^\circ\text{C}$
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 20 \text{ A}$

figure 30. FWD

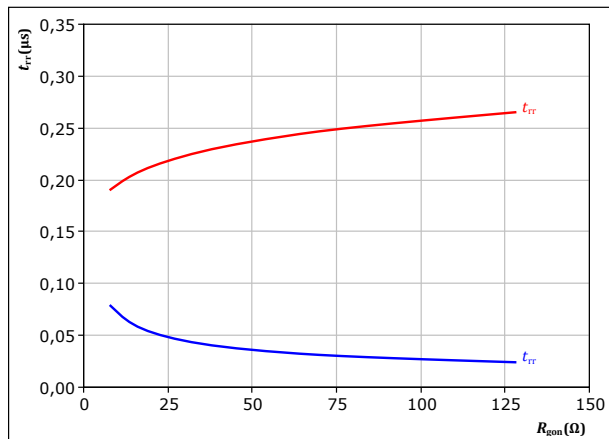
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $T_j: \text{ — } 25 \text{ }^\circ\text{C}$
 $\text{ — } 125 \text{ }^\circ\text{C}$

figure 31. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 20 \text{ A}$
 $T_j: \text{ — } 25 \text{ }^\circ\text{C}$
 $\text{ — } 125 \text{ }^\circ\text{C}$

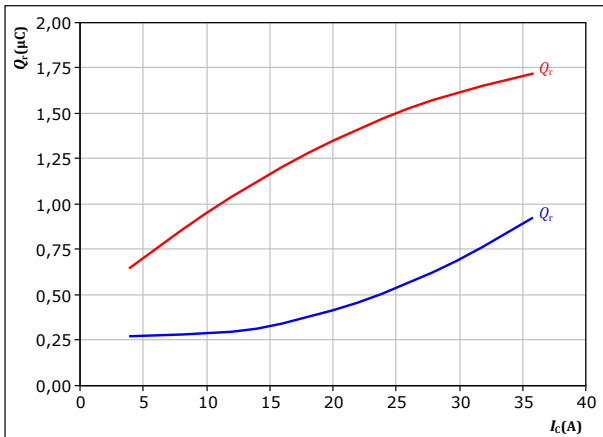


Inverter Switching Characteristics

figure 32. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

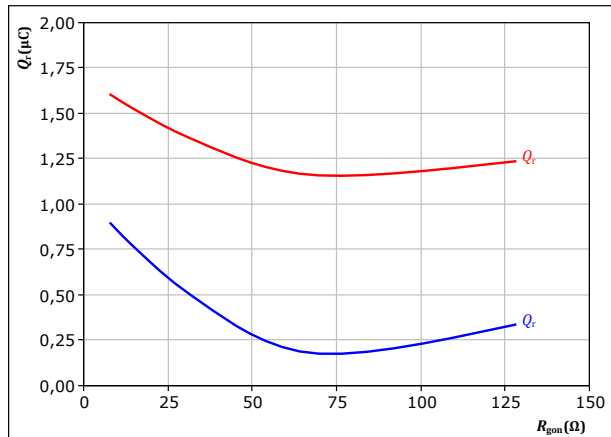
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
— 125 °C

figure 33. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

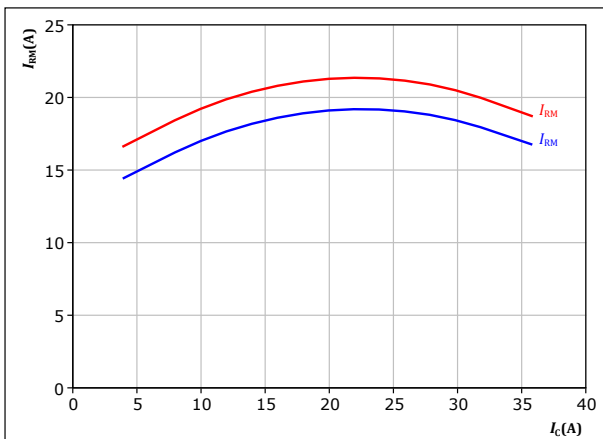
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_c = 20$ A

T_j : — 25 °C
— 125 °C

figure 34. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

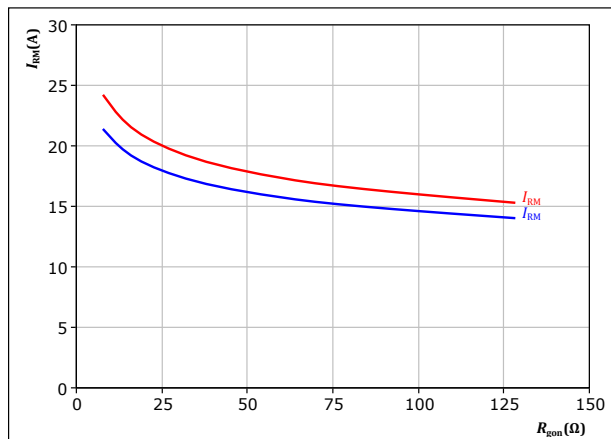
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
— 125 °C

figure 35. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_c = 20$ A

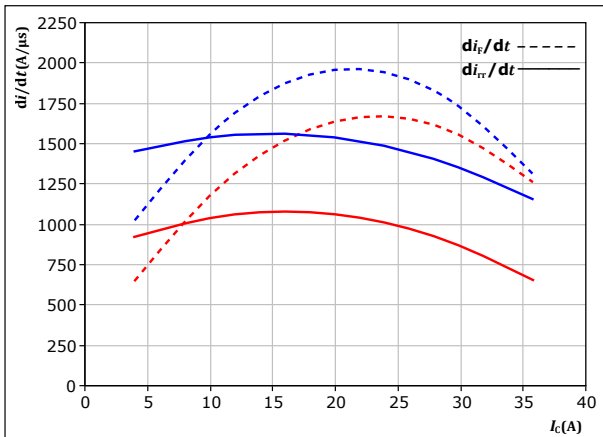
T_j : — 25 °C
— 125 °C



Inverter Switching Characteristics

figure 36. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$



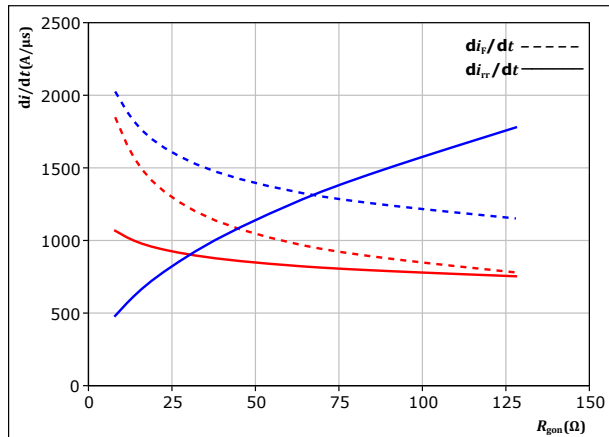
With an inductive load at

$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
 — 125 °C

figure 37. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



With an inductive load at

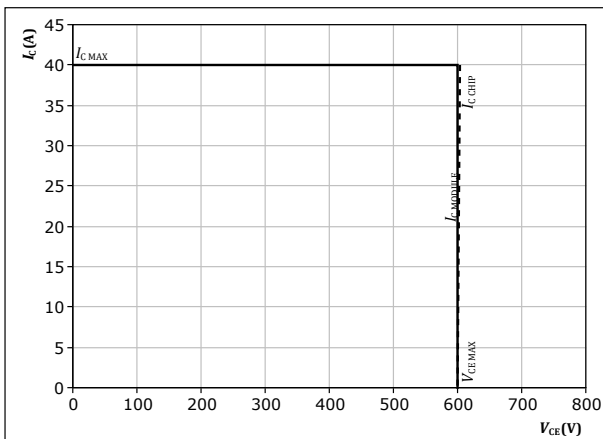
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_C = 20$ A

T_j : — 25 °C
 — 125 °C

figure 38. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



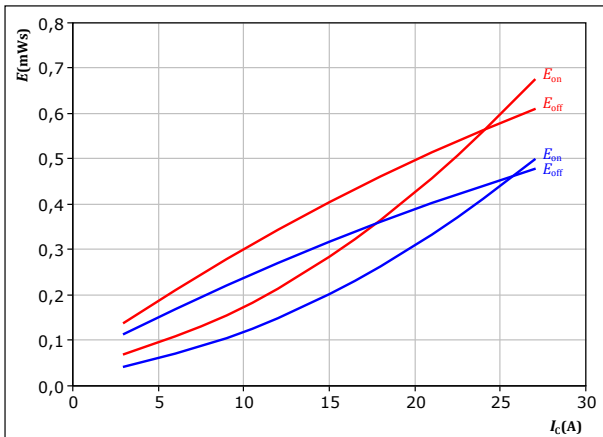
At $T_j = 125$ °C
 $R_{gon} = 16$ Ω
 $R_{goff} = 8$ Ω



Brake Switching Characteristics

figure 39. IGBT

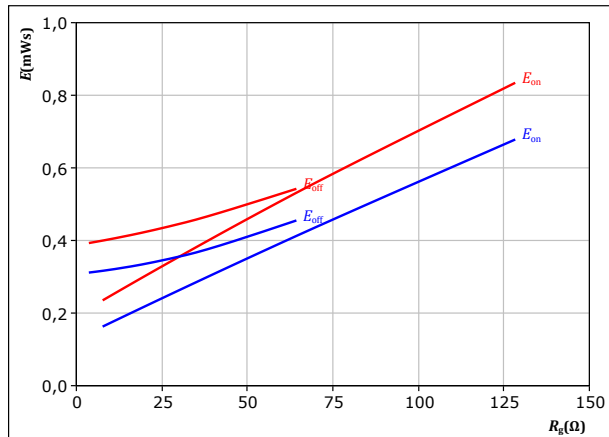
Typical switching energy losses as a function of collector current
 $E = f(I_c)$



With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 16 \ \Omega$
 $R_{goff} = 8 \ \Omega$
 $T_j: \text{ — } 25 \text{ }^\circ\text{C}$
 $\text{ — } 125 \text{ }^\circ\text{C}$

figure 40. IGBT

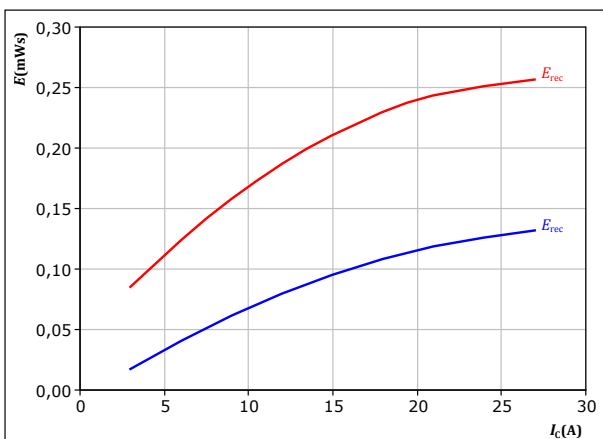
Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$



With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 15 \text{ A}$
 $T_j: \text{ — } 25 \text{ }^\circ\text{C}$
 $\text{ — } 125 \text{ }^\circ\text{C}$

figure 41. FWD

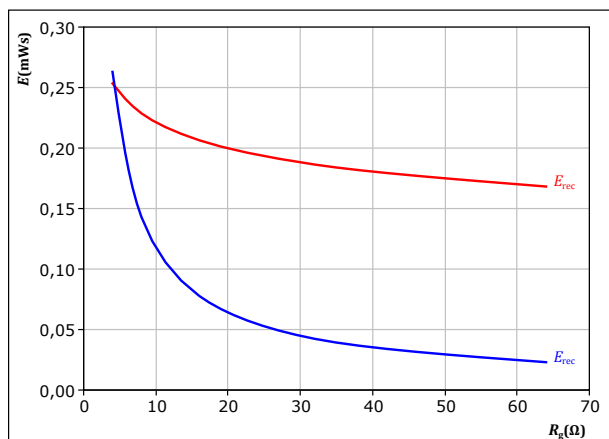
Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$



With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 16 \ \Omega$
 $T_j: \text{ — } 25 \text{ }^\circ\text{C}$
 $\text{ — } 125 \text{ }^\circ\text{C}$

figure 42. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



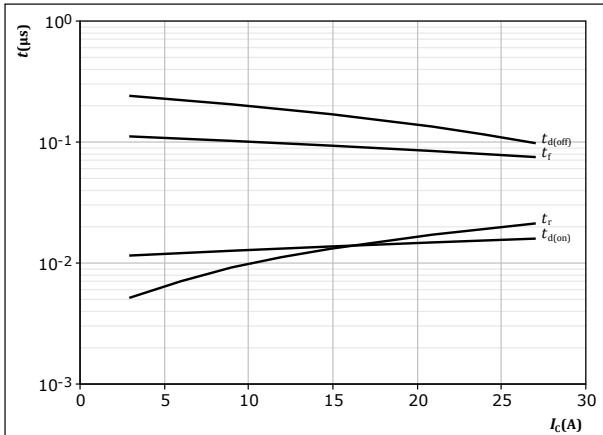
With an inductive load at
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 15 \text{ A}$
 $T_j: \text{ — } 25 \text{ }^\circ\text{C}$
 $\text{ — } 125 \text{ }^\circ\text{C}$



Brake Switching Characteristics

figure 43. IGBT

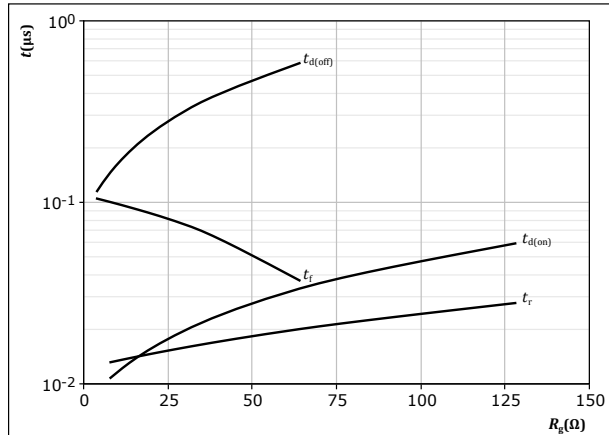
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 125$ °C
 $V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω
 $R_{goff} = 8$ Ω

figure 44. IGBT

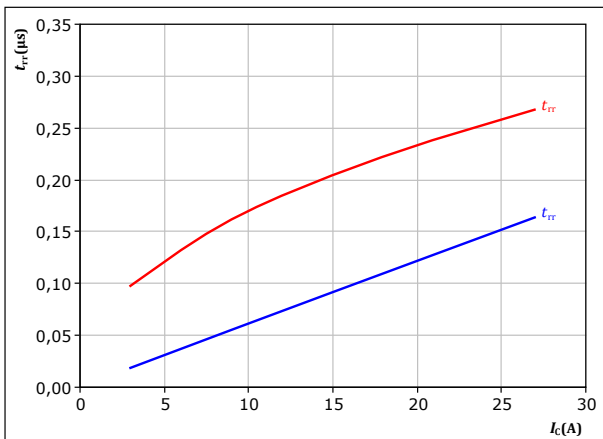
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 125$ °C
 $V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

figure 45. FWD

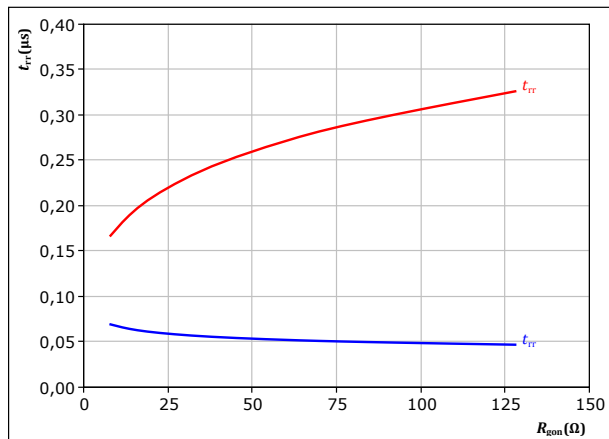
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at
 $V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω
 T_j : — 25 °C
— 125 °C

figure 46. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A
 T_j : — 25 °C
— 125 °C

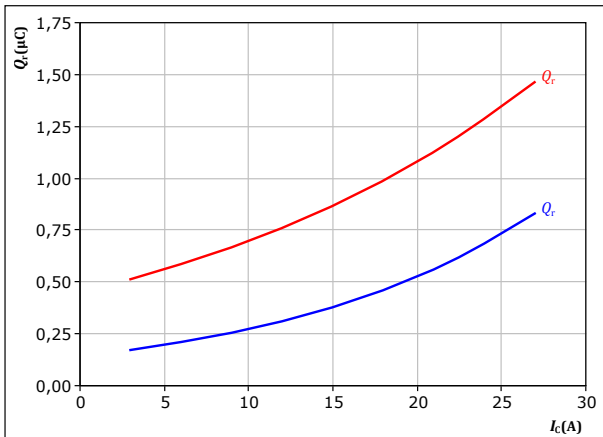


Brake Switching Characteristics

figure 47. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

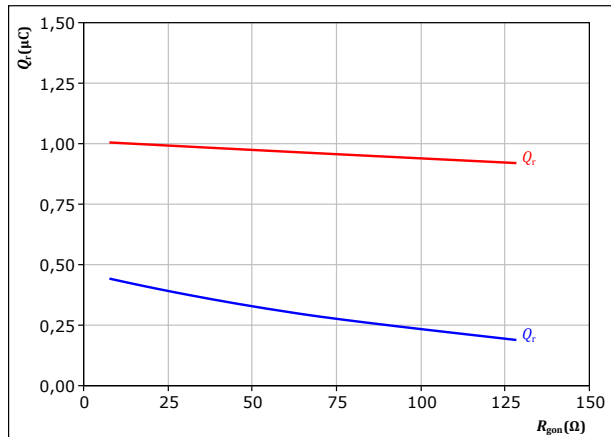
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
— 125 °C

figure 48. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

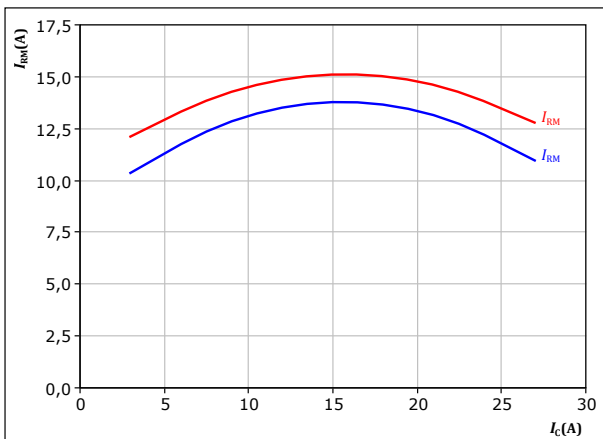
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

T_j : — 25 °C
— 125 °C

figure 49. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

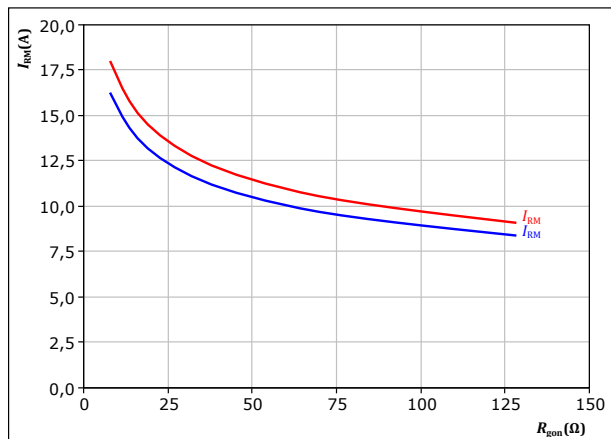
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
— 125 °C

figure 50. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

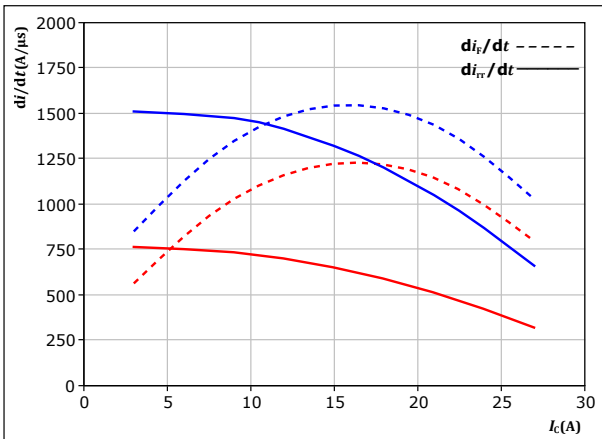
T_j : — 25 °C
— 125 °C



Brake Switching Characteristics

figure 51. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$



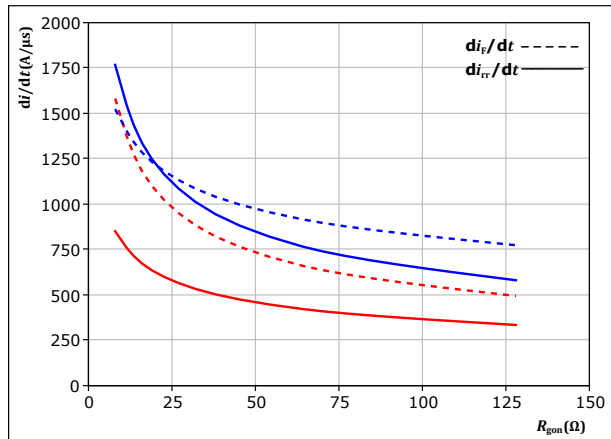
With an inductive load at

$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 16$ Ω

T_j : — 25 °C
 — 125 °C

figure 52. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



With an inductive load at

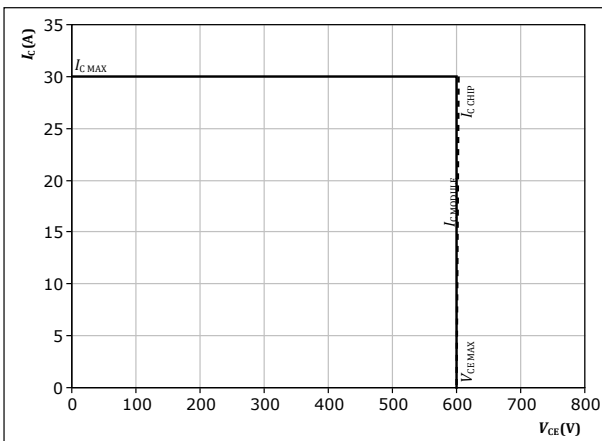
$V_{CE} = 300$ V
 $V_{GE} = 0/15$ V
 $I_C = 15$ A

T_j : — 25 °C
 — 125 °C

figure 53. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 125$ °C
 $R_{gon} = 16$ Ω
 $R_{goff} = 8$ Ω



Switching Definitions

figure 54. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

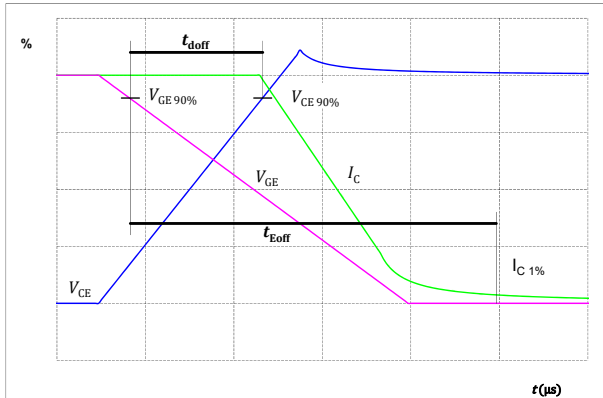


figure 55. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

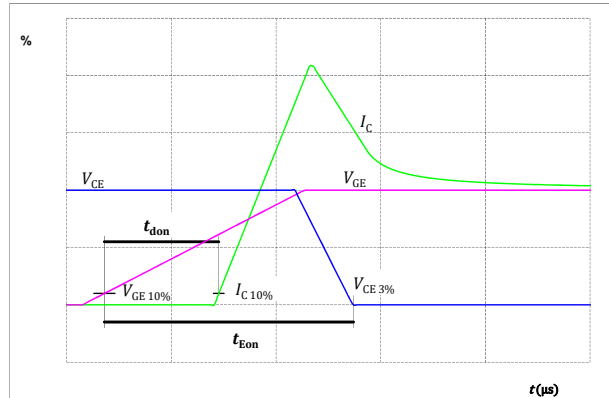


figure 56. IGBT

Turn-off Switching Waveforms & definition of t_f

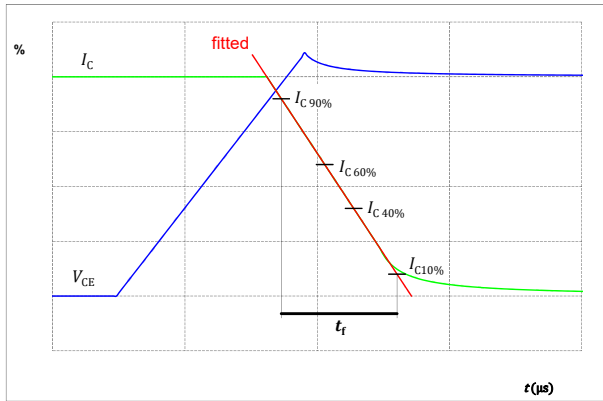
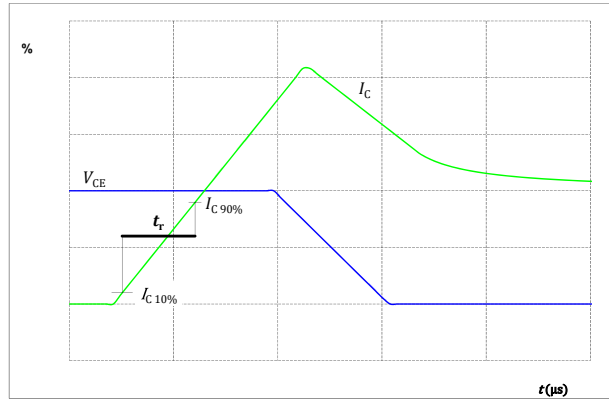


figure 57. IGBT

Turn-on Switching Waveforms & definition of t_r





Switching Definitions

figure 58. FWD

Turn-off Switching Waveforms & definition of t_{rr}

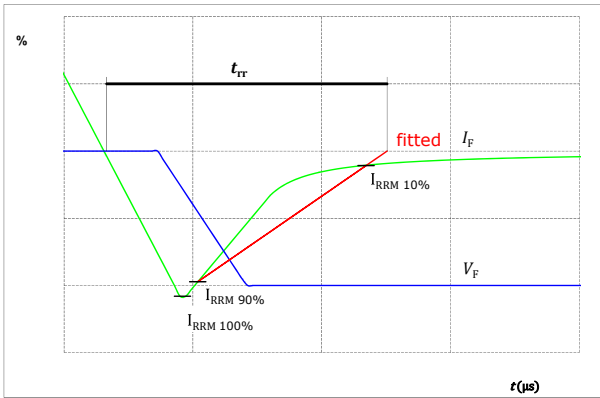
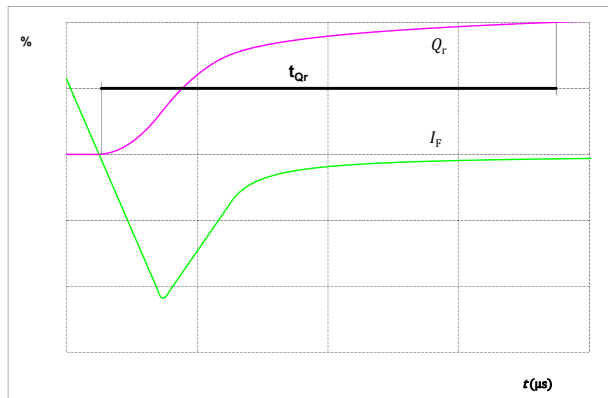



figure 59. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)

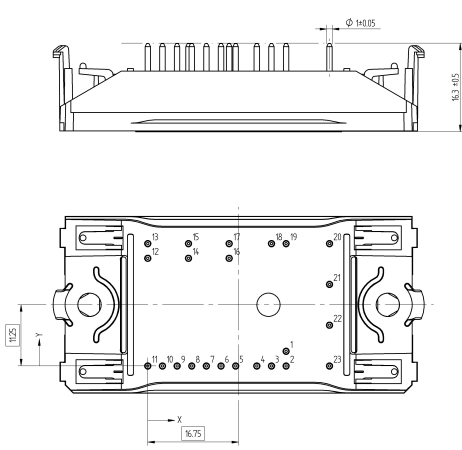




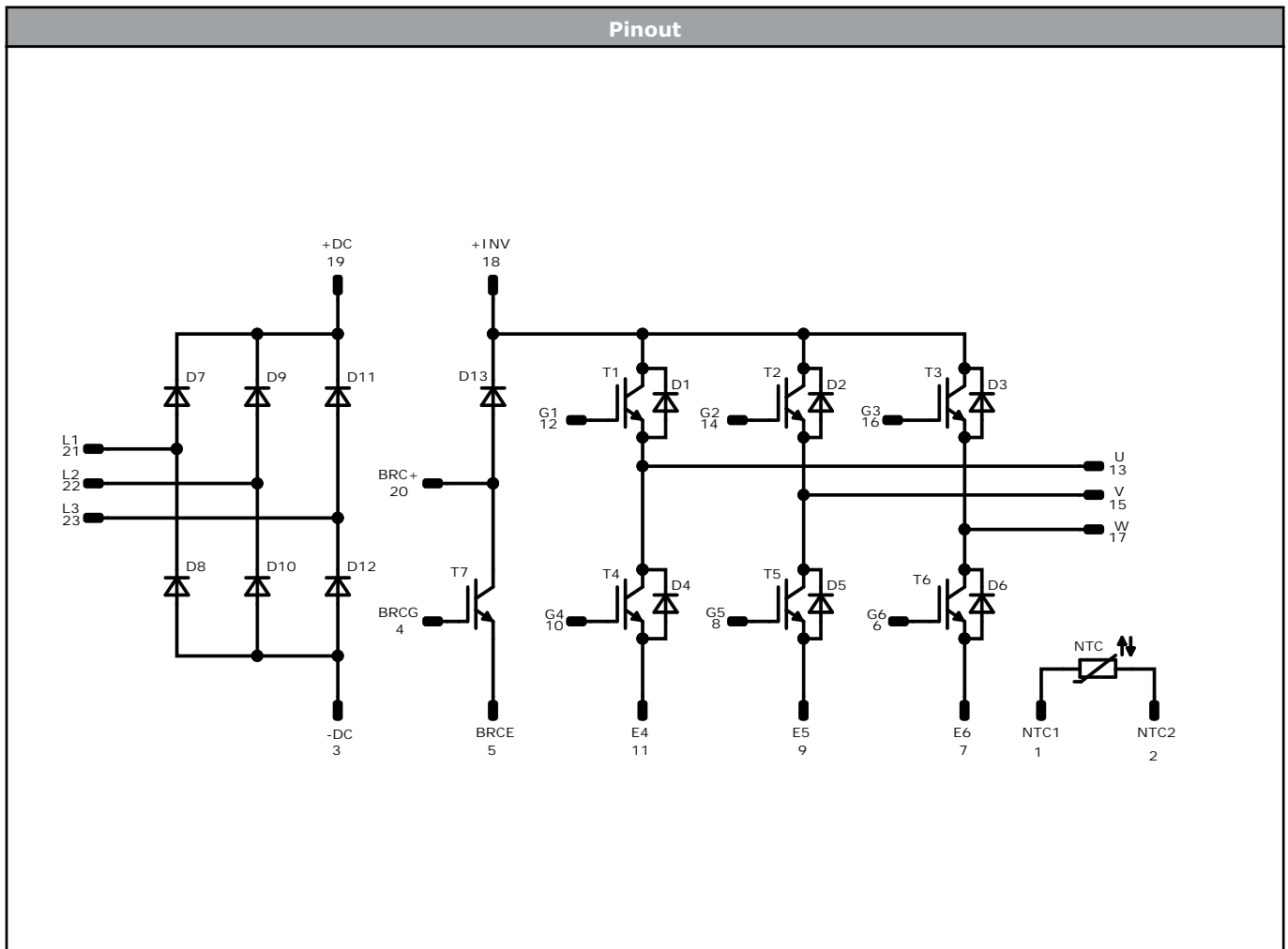
Ordering Code	
Version	Ordering Code
Without thermal paste	V23990-P545-A28-PM
With thermal paste (5,2 W/mK, PTM6000HV)	V23990-P545-A28-/7/-PM
With thermal paste (3,4 W/mK, PSX-P7)	V23990-P545-A28-/3/-PM

Marking							
	Text	VIN VIN	Date code WWYY	Type&Ver TTTTTTVV	UL UL	Lot LLLLL	Serial SSSS
	Datamatrix	Type&Ver	Lot number	Serial	Date code		
		TTTTTTVV	LLLLL	SSSS	WWYY		

Pin table [mm]				Outline
Pin	X	Y	Function	
1	25,5	2,7	NTC1	
2	25,5	0	NTC2	
3	22,8	0	-DC	
4	20,1	0	BRCG	
5	16,2	0	BRCE	
6	13,5	0	G6	
7	10,8	0	E6	
8	8,1	0	G5	
9	5,4	0	E5	
10	2,7	0	G4	
11	0	0	E4	
12	0	19,8	G1	
13	0	22,5	U	
14	7,5	19,8	G2	
15	7,5	22,5	V	
16	15	19,8	G3	
17	15	22,5	W	
18	22,8	22,5	+INV	
19	25,5	22,5	+DC	
20	33,5	22,5	BRC+	
21	33,5	15	L1	
22	33,5	7,5	L2	
23	33,5	0	L3	



Tolerance of pinpositions: ±0.5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance



Identification					
ID	Component	Voltage	Current	Function	Comment
T4, T1, T5, T2, T6, T3	IGBT	600 V	20 A	Inverter Switch	
D1, D4, D2, D5, D3, D6	FWD	600 V	20 A	Inverter Diode	
T7	IGBT	600 V	15 A	Brake Switch	
D13	FWD	600 V	15 A	Brake Diode	
D8, D7, D10, D9, D12, D11	Rectifier	1600 V	25 A	Rectifier Diode	
NTC	Thermistor			Thermistor	




Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow 0</i> packages see vincotech.com website.

Package data
Package data for <i>flow 0</i> packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-P545-A28-PM-D10-14	25 Sep. 2022	New Datasheet format, module is unchanged	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.